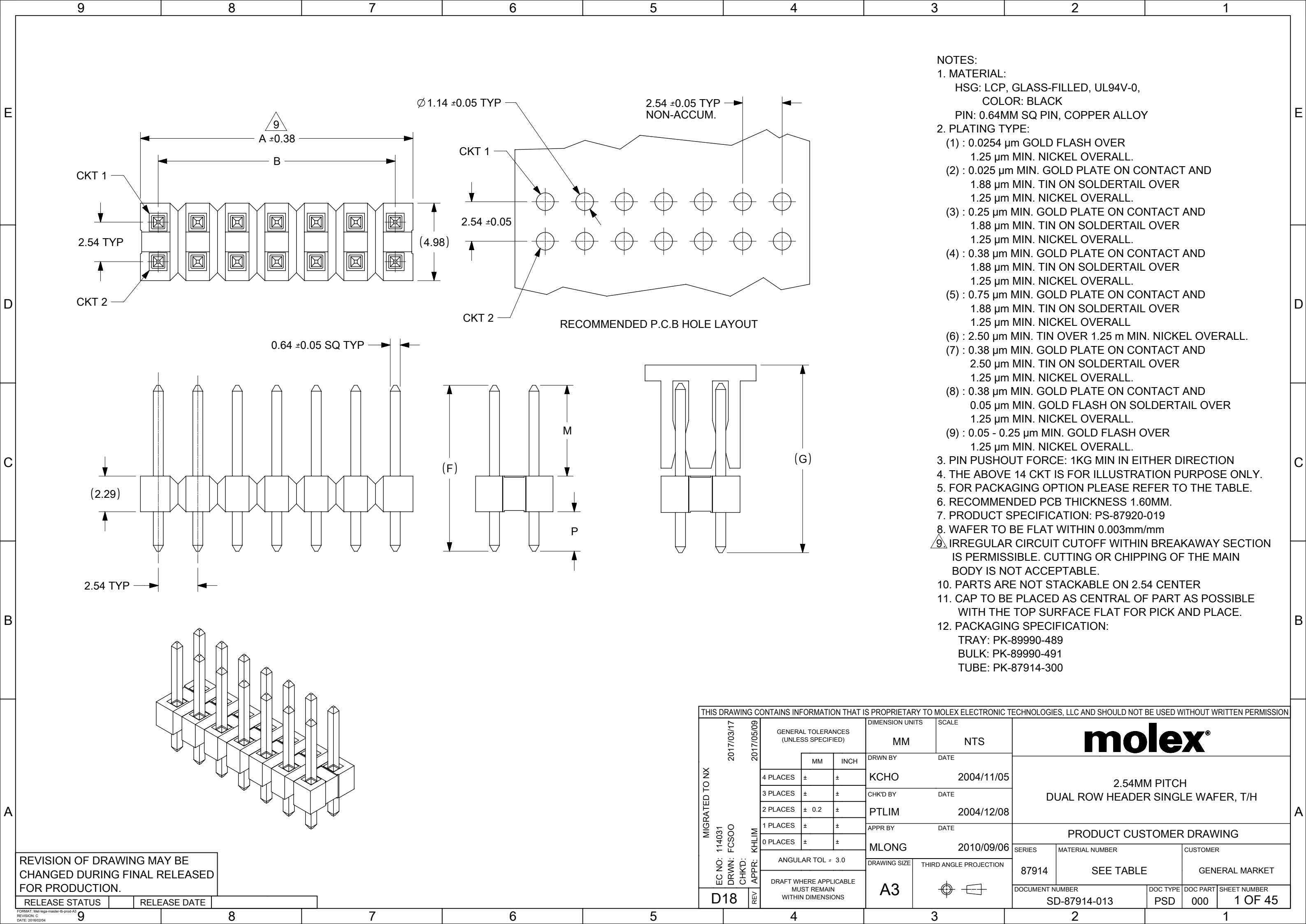
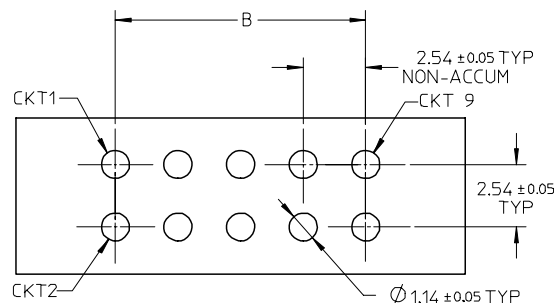
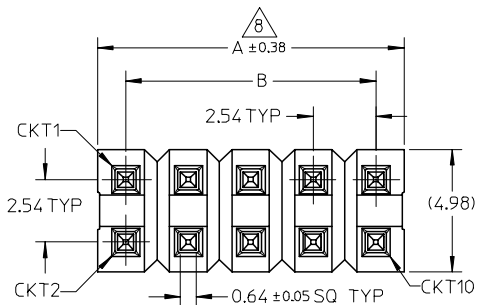
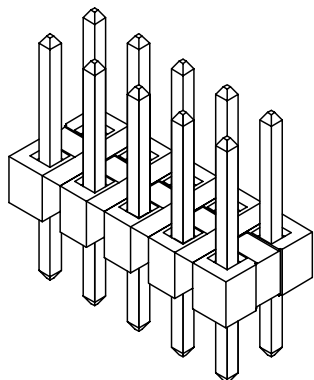
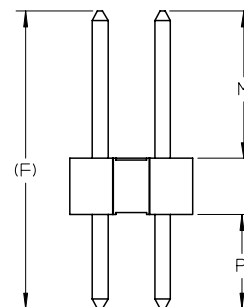
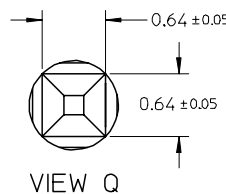
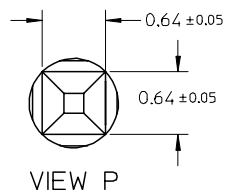
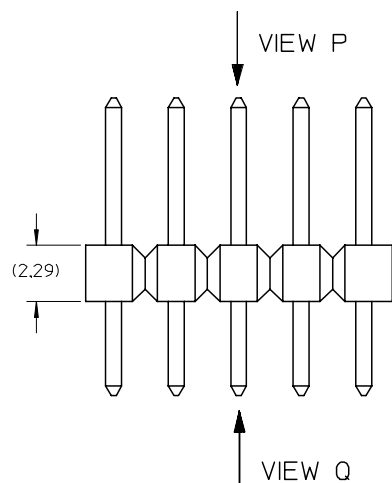






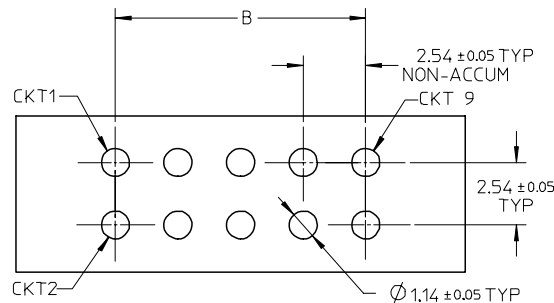
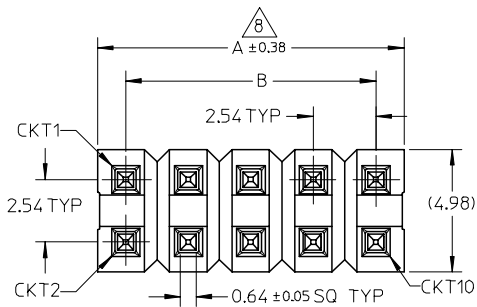
RECOMMENDED PCB LAYOUT



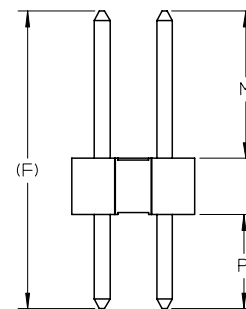
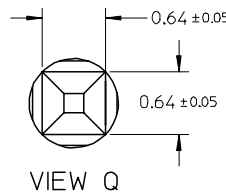
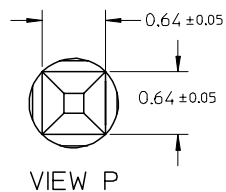
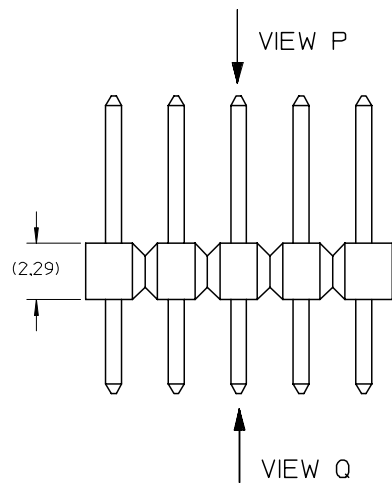
NOTES:

1. MATERIAL:
HSG: LCP, GLASS-FILLED, UL94V-0,
COLOR: BLACK
PIN: 0.64MM SQ PIN, COPPER ALLOY
2. PLATING TYPE:
(1) : 0.381 μ m MIN. GOLD PLATE ON CONTACT AND
1.905 μ m MIN. TIN ON SOLDERTAIL OVER
1.270 μ m MIN. NICKEL OVERALL.
(2) : 0.762 μ m MIN. GOLD PLATE ON CONTACT AND
1.905 μ m MIN. TIN ON SOLDERTAIL OVER
1.270 μ m MIN. NICKEL OVERALL.
(3) : 2.540 μ m MIN. TIN IN SELECTED AREA OVER
1.270 μ m MIN. NICKEL OVERALL.
3. THE ABOVE 10 CKT IS FOR ILLUSTRATION PURPOSE ONLY.
4. FOR PACKAGING OPTION PLEASE REFER TO THE TABLE.
5. RECOMMENDED PCB THICKNESS 1.60MM.
6. PRODUCT SPECIFICATION: PS-87920-019
7. WAFER TO BE FLAT WITHIN 0.003mm/mm
8. IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION
IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN
BODY IS NOT ACCEPTABLE.
9. PARTS ARE NOT STACKABLE ON 2.54 CENTER
10. PACKAGING SPECIFICATION:
TRAY: PK-89990-489
BULK: PK-89990-491

EWR# 1010 & 1021		QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
EC NO: S2007-0182		DESCRIPTION		mm		MM ONLY		NTS		METRIC			
2006/09/11		DRWN:SKL IM01		± ---		DRAWN BY		DATE		TITLE			
2006/09/12		CHKD:CWLAM		± ---		SKL IM01		2006/08/21		CUSTOM HEADER			
2006/09/13		APPR:KWLEE		± 0.2		CHECKED BY		DATE		C-GRID, SINGLE WAFER HDR,			
				± ---		CWLAM		2006/09/04		THROU HOLE, VERTICAL, LF			
				± ---		APPROVED BY		DATE		MOLEX INCORPORATED			
				ANGULAR ± 3 °		KWLEE		2006/09/04		MOLEX INCORPORATED			
						MATERIAL NO.		DOCUMENT NO.		SD-87914-059			
						SIZE		SEE TABLE		SHEET NO.			
						A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		1 OF 9			



RECOMMENDED PCB LAYOUT



NOTES:

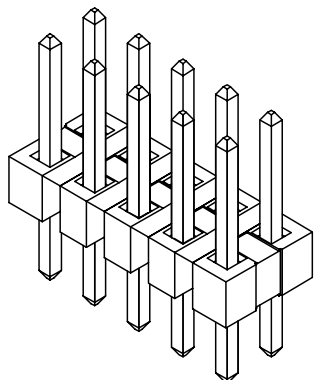
1. MATERIAL:

HSG: LCP, GLASS-FILLED, UL94V-0,
COLOR: BLACK
PIN: 0.64MM SQ PIN, COPPER ALLOY

2. PLATING TYPE:

- (1) : 0.381 μ m MIN. GOLD PLATE ON CONTACT AND 1.905 μ m MIN. TIN ON SOLDER TAIL OVER 1.270 μ m MIN. NICKEL OVERALL.
- (2) : 0.762 μ m MIN. GOLD PLATE ON CONTACT AND 1.905 μ m MIN. TIN ON SOLDER TAIL OVER 1.270 μ m MIN. NICKEL OVERALL.
- (3) : 2.540 μ m MIN. TIN IN SELECTED AREA OVER 1.270 μ m MIN. NICKEL OVERALL.

3. THE ABOVE 10 CKT IS FOR ILLUSTRATION PURPOSE ONLY.
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5. RECOMMENDED PCB THICKNESS 1.60MM.
6. PRODUCT SPECIFICATION: PS-87920-019
7. WAFER TO BE FLAT WITHIN 0.003mm/mm
8. IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE.
9. PARTS ARE NOT STACKABLE ON 2.54 CENTER
10. PACKAGING SPECIFICATION:
TRAY: PK-89990-489
BULK: PK-89990-491



EWR# 1010 & 1021 EC NO: S2007-0182 DRWN:SKL IM01 CHKD:CWLAM APPR:KWLEE	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		
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